



Semiconductor Device Type: MT / PL (H7X) 100 LQFP 14x14x1.6mm Matte Tin			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			JEDEC 97 Product Marking and/or Pkg. Labeling e3
Basic Substance	CAS Number	Contained in Sub-Component	% Total Weight	mg/part	ppm	491.77 (mg) Total	Mold Compound	% of Total Weight	84.73
Silica Fused	60676-86-0	Mold Compound	74.791	434.088	747,912		Silica Fused	60676-86-0	88.27
Epoxy Resin	Trade Secret	Mold Compound	5.287	30.687	52,872		Epoxy Resin	Trade Secret	6.24
Phenol Resin	Trade Secret	Mold Compound	4.397	25.523	43,975		Phenol Resin	Trade Secret	5.19
Carbon Black	1333-86-4	Mold Compound	0.254	1.475	2,542		Carbon Black	1333-86-4	0.30
Copper	7440-50-8	Lead Frame	12.172	70.645	121,718				
Nickel	7440-02-0	Lead Frame	0.325	1.884	3,246	74.18 (mg) Total	Lead Frame	7440-02-0	95.24
Silver	7440-22-4	Lead Frame	0.213	1.238	2,133		Copper	7440-50-8	2.54
Silicon	7440-21-3	Lead Frame	0.058	0.334	575		Nickel	7440-02-0	1.67
Magnesium	7439-95-4	Lead Frame	0.013	0.074	128		Silver	7440-22-4	0.45
Silver	7440-22-4	Die Attach	0.031	0.179	308		Silicon	7440-21-3	0.10
Acrylic Resin	Trade secret	Die Attach	0.003	0.020	34		Magnesium	7439-95-4	
Epoxy Resin	Trade secret	Die Attach	0.001	0.006	10				
Acrylated EP-Resin	Trade secret	Die Attach	0.002	0.013	22	0.23 (mg) Total	Die Attach	7440-22-4	77.00
Polybutadiene derivative & Copolymer	9003-17-2	Die Attach	0.003	0.015	26		Silver	7440-22-4	8.50
Silicon	7440-21-3	Chip (Die)	0.570	3.308	5,700		Acrylic Resin	Trade secret	2.50
Copper	7440-50-8	Wire Bond	0.098	0.570	983		Epoxy Resin	Trade secret	5.50
Palladium	7440-05-3	Wire Bond	0.002	0.010	18		Acrylated EP-Resin	Trade secret	7
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.780	10.331	17,900		Polybutadiene derivative & Copolymer	9003-17-2	
TOTALS:			100.000	580.400	1,000,000				
0.5804 g Total Mass									
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)									
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and/or analytical test data.									
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.									
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offering/industries/chemicals/plastics/									
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.									
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table									
						3.31 (mg) Total	Chip (Die)	% of Total Weight	0.57
							Doped Silicon	7440-21-3	100.00
						Total 100.00			
						0.58 (mg) Total	Wire Bond	% of Total Weight	0.1
							Copper	7440-50-8	98.25
							Palladium	7440-05-3	1.75
						Total 100.00			
						10.33 (mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	1.78
							Tin	7440-31-5	100.00
						Total 100.00			
						580.400			100.000